

Parameter	Ratings	Units
Blocking Voltage	400	V_P
Load Current	150	mA_{rms} / mA_{DC}
On-Resistance (max)	25	Ω

Features

- Current Limiting
- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- No EMI/RFI Generation
- Small 6-Pin Package
- Flammability Rating UL 94 V-0
- Surface Mount and Tape & Reel Version Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Industrial Controls

Description

PLA110L is a current-limited, normally open (1-Form-A) solid state relay that uses optically coupled MOSFET technology to provide 3750V_{rms} of input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

The PLA110L can be used to replace mechanical relays. It offers the superior reliability associated with semiconductor devices, it has no moving parts, and it offers faster, bounce-free switching in a more compact surface mount or thru-hole package.

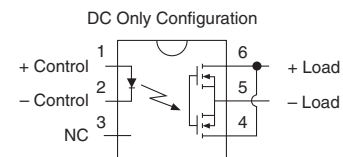
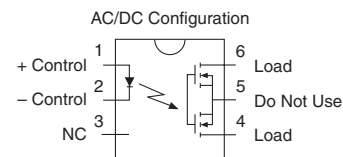
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 62368-1 Certified Component: TUV Certificate B 082667 0008

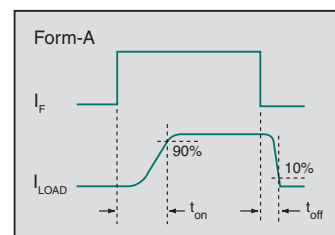
Ordering Information

Part #	Description
PLA110L	6-Pin Dip (50/Tube)
PLA110LS	6-Pin Surface Mount (50/Tube)
PLA110LSTR	6-Pin Surface Mount (1000/Reel)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Symbol	Ratings	Units
Blocking Voltage	$V_{L(max)}$	400	V_P
Reverse Input Voltage	V_R	5	V
Input Control Current	I_F	50	mA
Peak (10ms)		1	A
Input Power Dissipation ¹	P_{IN}	150	mW
Total Power Dissipation ²	P_T	800	mW
Isolation Voltage Input to Output	V_{ISO}	3750	V_{rms}
Operational Temperature, Ambient	T_A	-40 to +85	°C
Storage Temperature	T_{STG}	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

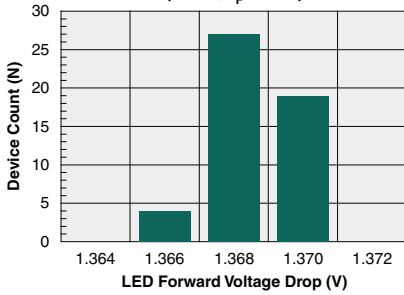
Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

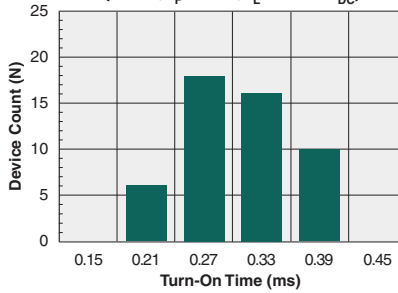
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Blocking Voltage	$I_L=1\mu A$	$V_{L(max)}$	400	-	-	V
Load Current, Continuous	-	I_L	-	-	150	mA_{rms} / mA_{DC}
AC/DC Configuration			-	-	250	mA_{DC}
On-Resistance	$I_L=150mA$	R_{ON}	-	-	25	Ω
AC/DC Configuration			$I_L=250mA$	-	-	
DC Configuration						
Off-State Leakage Current	$V_L=400V_P$	I_{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	$I_F=5mA, V_L=10V$	t_{on}	-	-	1	ms
Turn-Off		t_{off}	-	-	0.5	ms
Output Capacitance	$I_F=0mA, V_L=50V, f=1MHz$	C_{OUT}	-	25	-	pF
Load Current Limiting	-	I_{CL}	190	235	280	mA
Input Characteristics						
Input Control Current to Activate	$I_L=150mA$	I_F	-	-	5	mA
Input Control Current to Deactivate	-	I_F	0.4	0.7	-	mA
Input Voltage Drop	$I_F=5mA$	V_F	0.9	1.35	1.5	V
Reverse Input Current	$V_R=5V$	I_R	-	-	10	μA
Common Characteristics						
Input to Output Capacitance	$V_{IO}=0V, f=1MHz$	C_{IO}	-	3	-	pF

PERFORMANCE DATA*

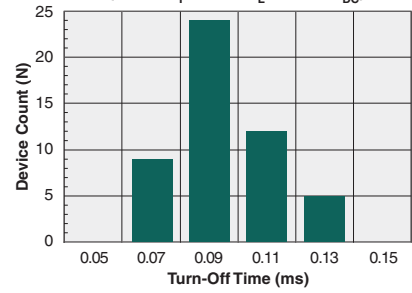
Typical LED Forward Voltage Drop
(N=50, $I_F=5\text{mA}$)



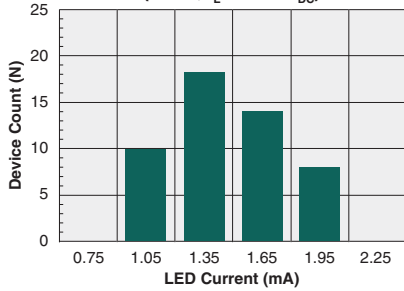
Typical Turn-On Time
(N=50, $I_F=5\text{mA}$, $I_L=150\text{mA}_{DC}$)



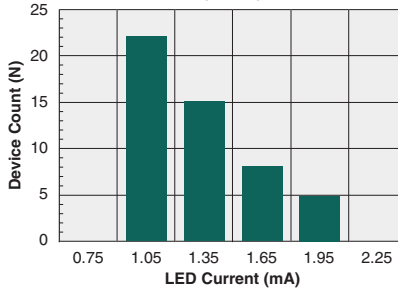
Typical Turn-Off Time
(N=50, $I_F=5\text{mA}$, $I_L=150\text{mA}_{DC}$)



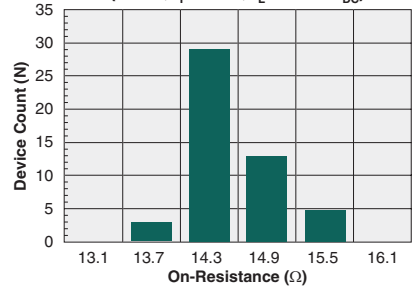
Typical I_F for Switch Operation
(N=50, $I_L=150\text{mA}_{DC}$)



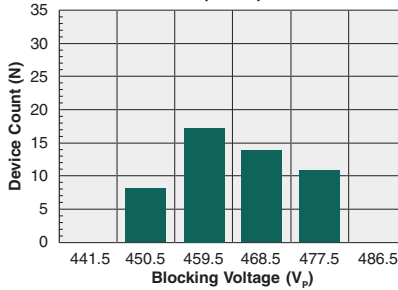
Typical I_F for Switch Dropout
(N=50)



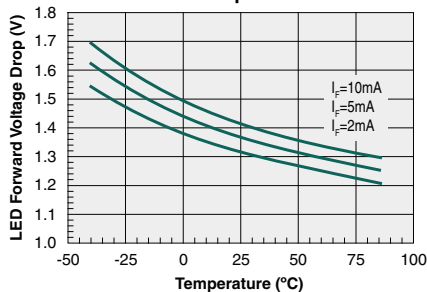
Typical On-Resistance Distribution
(N=50, $I_F=5\text{mA}$, $I_L=150\text{mA}_{DC}$)



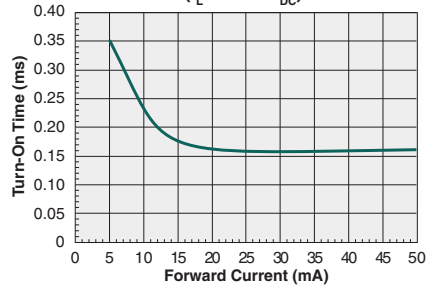
Typical Blocking Voltage Distribution
(N=50)



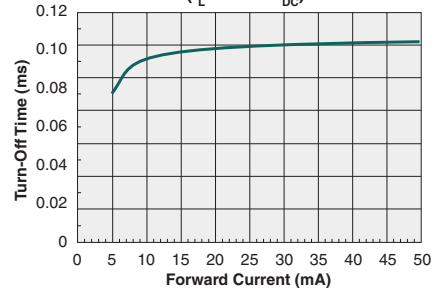
Typical LED Forward Voltage Drop vs. Temperature



Typical Turn-On Time vs. LED Forward Current
($I_L=150\text{mA}_{DC}$)



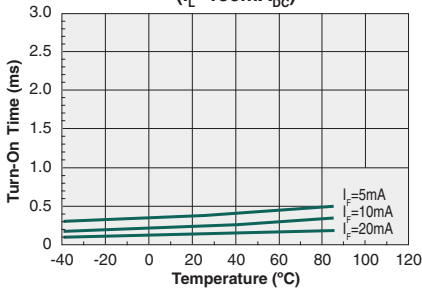
Typical Turn-Off Time vs. LED Forward Current
($I_L=150\text{mA}_{DC}$)



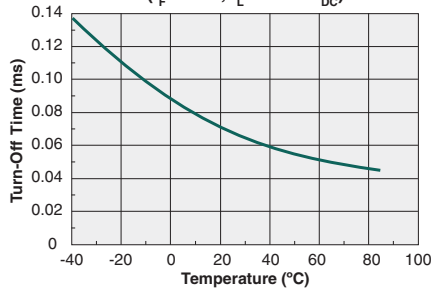
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

PERFORMANCE DATA*

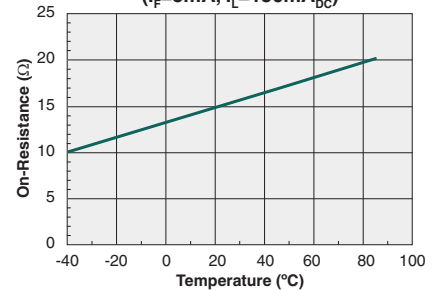
Typical Turn-On Time vs. Temperature
($I_L=150\text{mA}_{DC}$)



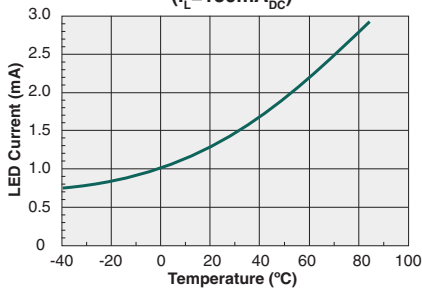
Typical Turn-Off Time vs. Temperature
($I_F=5\text{mA}, I_L=150\text{mA}_{DC}$)



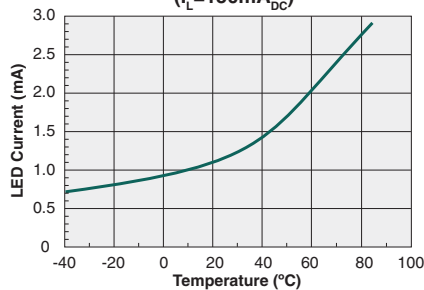
Typical On-Resistance vs. Temperature
($I_F=5\text{mA}, I_L=150\text{mA}_{DC}$)



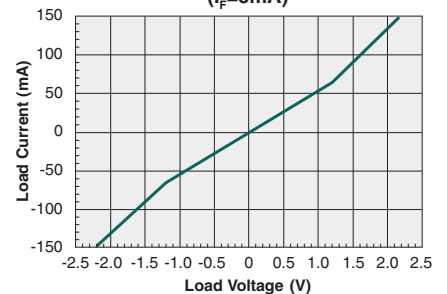
Typical I_F for Switch Operation vs. Temperature
($I_L=150\text{mA}_{DC}$)



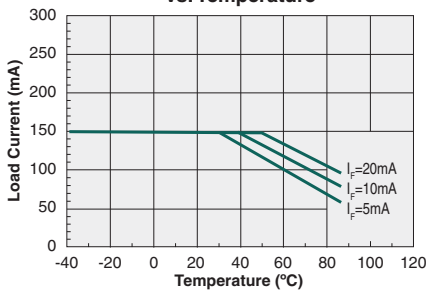
Typical I_F for Switch Dropout vs. Temperature
($I_L=150\text{mA}_{DC}$)



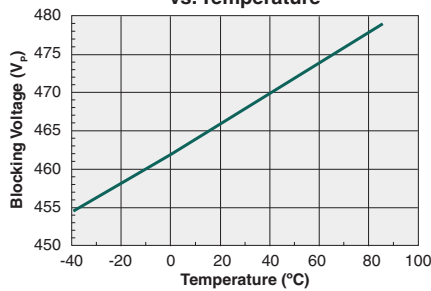
Typical Load Current vs. Load Voltage
($I_F=5\text{mA}$)



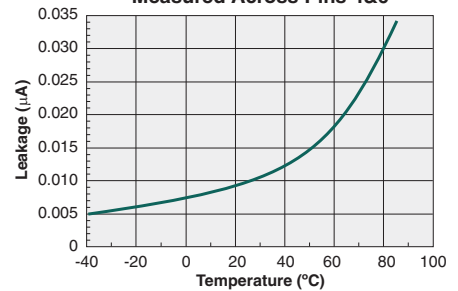
Maximum Load Current vs. Temperature



Typical Blocking Voltage vs. Temperature




Typical Leakage vs. Temperature Measured Across Pins 4&6



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

Manufacturing Information

Moisture Sensitivity

 All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
PLA110LS	MSL 1

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature (T_C) and the maximum total dwell time (t_p) in all reflow processes that the body temperature of these surface mount devices may be ($T_C - 5$)°C or greater. The device's body temperature must not exceed the Classification Temperature at any time during reflow soldering processes.

Device	Classification Temperature (T_C)	Dwell Time (t_p)	Max Reflow Cycles
PLA110LS	250°C	30 seconds	3

For through-hole devices, the maximum solder temperature and the maximum total dwell time in all solder waves that the device pins (leads) may be at the maximum solder temperature is given in the table below. The temperature of the body of the device must not exceed the max body temperature shown below at any time during the soldering process.

Device	Max Solder Temperature	Max Body Temperature	Max Total Dwell Time	Wave Cycles
PLA110L	260°C	250°C	10 seconds	1

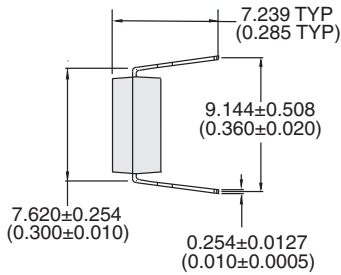
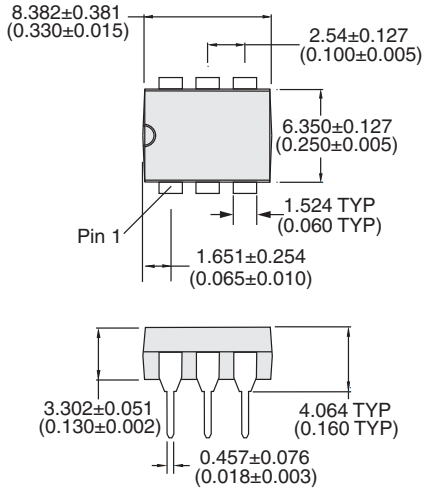
Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

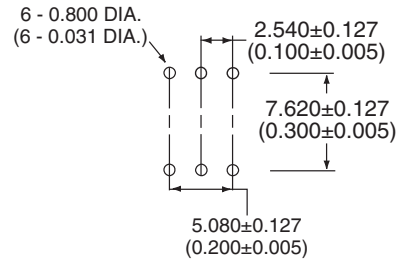


Mechanical Dimensions

PLA110L



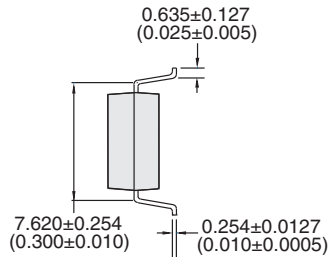
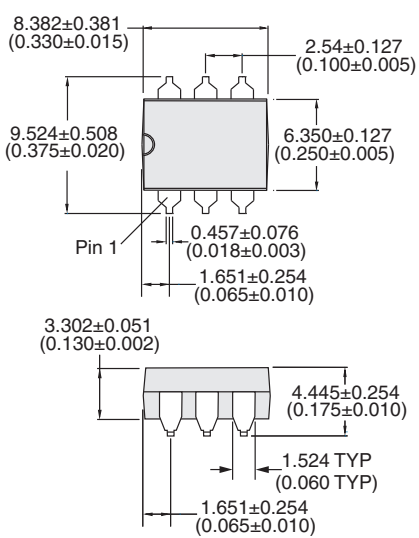
PCB Hole Pattern



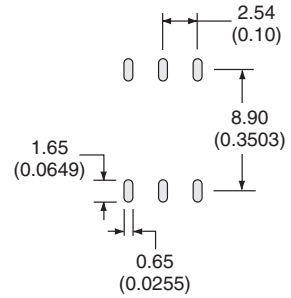
Controlling dimension: inches

Dimensions
mm
(inches)

PLA110LS



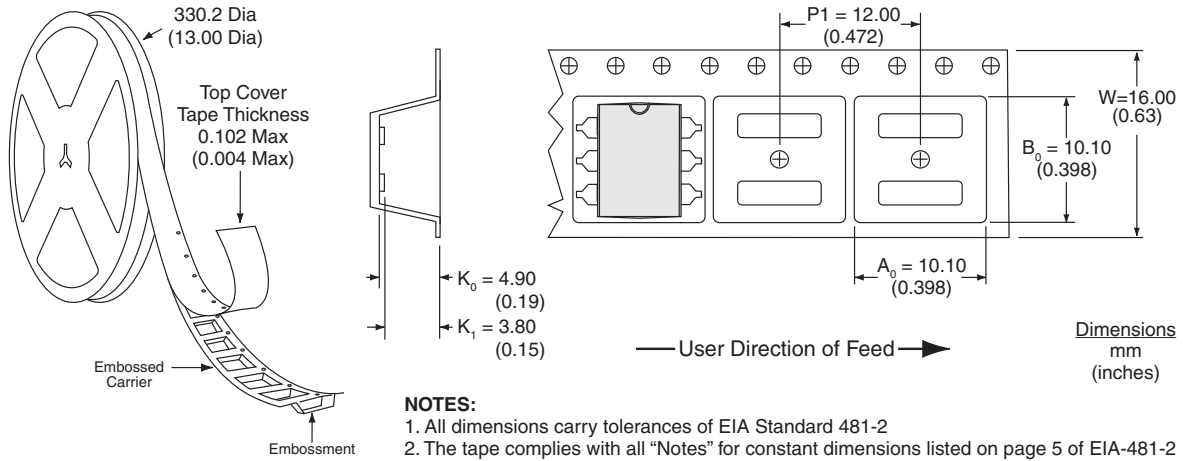
PCB Land Pattern



Controlling dimension: inches

Dimensions
mm
(inches)

PLA110LSTR Tape & Reel



For additional information please visit our website at: <https://www.ixysic.com>